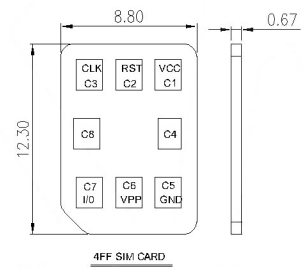
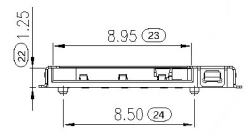
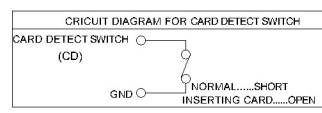


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

PAD
 KEEP OUT AREA



- NOTES:
- MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
TERMINAL: COPPER ALLOY
SHELL: SUS
 - PLATING:
SUS
TERMINAL:
CONTACT AREA: AU GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
 - SPECIALITY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 50mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±0.5℃, 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature -40℃ ~ +85℃;
Humidity 80% R.H MAX



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	IO

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN
Δ X					ANGULAR ±5°			VIEW:	PART NO.:
Δ X					L ≤ 4 ±0.2			UNIT: mm	DWG NO.:
Δ X					4 < L ≤ 16 ±0.3			SIZE: A4	XKNANO-113
Δ X					16 < L ≤ 63 ±0.4				WEIGHT
MARK					L > 63 ±0.5				1.0g
									SHEET
									1/1
									REVISION
									A0